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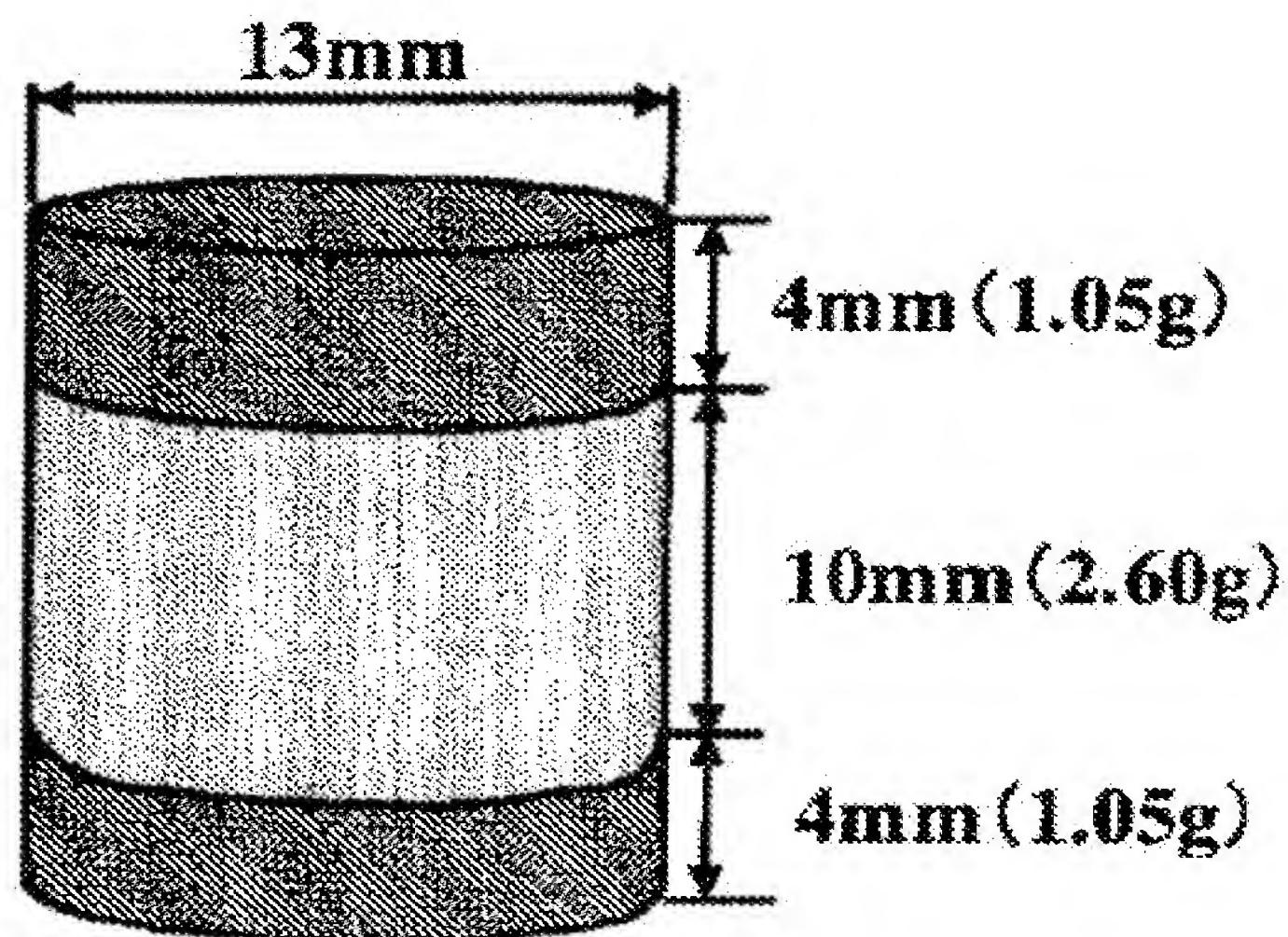
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TITLE : EPOXY RESIN COMPOSITION TABLET
FOR SEALING SEMICONDUCTOR
AND SEMICONDUCTOR DEVICE
MADE BY SEALING WITH THE TABLET



ABSTRACT : PROBLEM TO BE SOLVED: To provide a group of epoxy resin compositions excellent in moldability.

SOLUTION: This epoxy resin composition tablet used for sealing a semiconductor, containing an epoxy resin, a curing agent and an inorganic filler is characterized in that it is made from a group of two or more epoxy resin compositions different in the content of a mold release agent, the adhesive power under shear, or the glass transition temperature. A semiconductor device is obtained by transfer molding using the tablet.

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